

DUAL CMOS SyncFIFO™ DUAL 256 x 9, DUAL 512 x 9, DUAL 1,024 x 9, DUAL 2,048 x 9, DUAL 4,096 x 9, DUAL 8,192 x 9 IDT72801 IDT72811 IDT72821 IDT72831 IDT72841 IDT72851

#### **FEATURES:**

- The IDT72801 is equivalent to two IDT72201 256 x 9 FIFOs
- The IDT72811 is equivalent to two IDT72211 512 x 9 FIFOs
- The IDT72821 is equivalent to two IDT72221 1.024 x 9 FIFOs
- The IDT72831 is equivalent to two IDT72231 2,048 x 9 FIFOs
- The IDT72841 is equivalent to two IDT72241 4,096 x 9 FIFOs
- The IDT72851 is equivalent to two IDT72251 8,192 x 9 FIFOs
- Offers optimal combination of large capacity, high speed, design flexibility and small footprint
- Ideal for prioritization, bidirectional, and width expansion applications
- 10 ns read/write cycle time for the IDT72801/72811/72821/72831/ 72841 (excluding the IDT72851)
- 15 ns read/write cycle time for the IDT72851
- Separate control lines and data lines for each FIFO
- Separate Empty, Full, Programmable Almost-Empty and Almost-Full flags for each FIFO
- · Enable puts output data lines in high-impedance state
- Space-saving 64-pin Thin Quad Flat Pack (TQFP) and Slim Thin Quad Flatpack (STQFP)
- Industrial temperature range (-40°C to +85°C) is available

#### **DESCRIPTION:**

The IDT72801/72811/72821/72831/72841/72851 are dual synchronous (clocked) FIFOs. The device is functionally equivalent to two IDT72201/72211/72221/72231/72241/72251 FIFOs in a single package with all associated control, data, and flag lines assigned to separate pins.

Each of the two FIFOs (designated FIFO A and FIFO B) contained in the IDT72801/72811/72821/72831/72841/72851 has a 9-bit input data port (DA0 - DA8, DB0 - DB8) and a 9-bit output data port (QA0 - QA8, QB0 - QB8). Each input port is controlled by a free-running clock (WCLKA, WCLKB), and two Write Enable pins (WENA1, WENA2, WENB1, WENB2). Data is written into each of the two arrays on every rising clock edge of the Write Clock (WCLKA, WCLKB) when the appropriate write enable pins are asserted.

The output port of each FIFO bank is controlled by its associated clock pin (RCLKA, RCLKB) and two Read Enable pins (RENA1, RENA2, RENB1, RENB2). The Read Clock can be tied to the Write Clock for single clock operation or the two clocks can run asynchronous of one another for dual clock operation. An Output Enable pin (OEA, OEB) is provided on the read port of each FIFO for three-state output control.

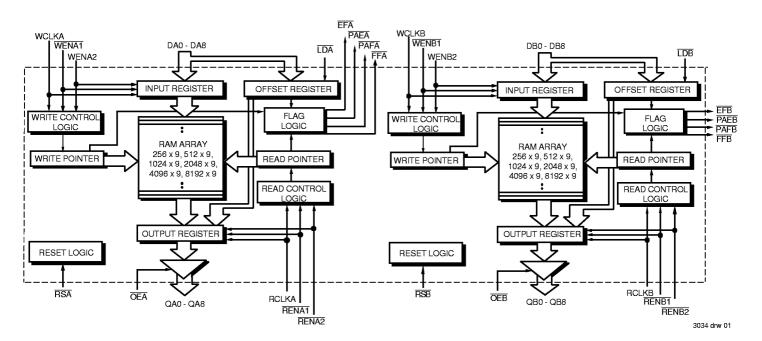
Each of the two FIFOs has two fixed flags, Empty (EFA, EFB) and Full (FFA, FFB). Two programmable flags, Almost-Empty (PAEA, PAEB) and Almost-Full (PAFA, PAFB), are provided for each FIFO bank to improve memory utilization. If not programmed, the programmable flags default to empty+7 for PAEA and PAEB, and full-7 for PAFA and PAFB.

The IDT72801/72811/72821/72831/72841/72851 architecture lends itself to many flexible configurations such as:

- · 2-level priority data buffering
- · Bidirectional operation
- Width expansion
- Depth expansion

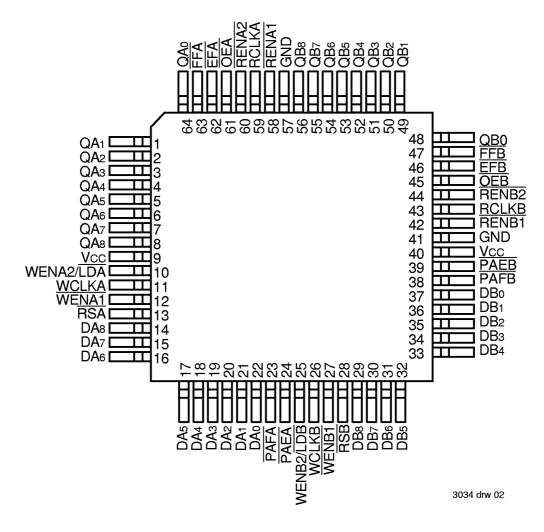
These FIFOs is fabricated using IDT's high-performance submicron CMOS technology.

#### **FUNCTIONAL BLOCK DIAGRAM**



**DECEMBER 1998** 

## PIN CONFIGURATION



TQFP (PN64-1, order code: PF) STQFP (PP64-1, order code: TF) TOP VIEW

#### NOTE

1. The STQFP package is not available for the IDT72851.

# **PIN DESCRIPTIONS**

The IDT72801/72811/72821/72831/72841/72851s two FIFOs, referred to as FIFO A and FIFO B, are identical in every respect. The following

description defines the input and output signals for FIFO A. The corresponding signal names for FIFO B are provided in parentheses.

Symbol	Name	I/O	Description
DA0-DA8	A Data Inputs	1	9-bit data inputs to RAM array A.
DB0-DB8	B Data Inputs	I	9-bit data inputs to RAM array B.
RSA, RSB	Reset	_	When RSA (RSB) is set LOW, the associated internal read and write pointers of array A (B) are set to the first location; FFA (FFB) and PAFA (PAFB) go HIGH, and PAEA (PAEB) and EFA (EFB) go LOW. After power-up, a reset of both FIFOs A and B is required before an initial Write.
WCLKA WCLKB	Write Clock	ı	Data is written into the FIFO A (B) on a LOW-to-HIGH transition of WCLKA (WCLKB) when the write enable(s) are asserted.
WENA1 WENB1	Write Enable 1	1	If FIFO A (B) is configured to have programmable flags, WENAT (WENBT) is the only Write Enable pin that can be used. When WENAT (WENBT) is LOW, data A (B) is written into the FIFO on every LOW-to-HIGH transition WCLKA (WCLKB). If the FIFO is configured to have two write enables, WENAT (WENBT) must be LOW and WENA2 (WENB2) must be HIGH to write data into the FIFO. Data will not be written into the FIFO if FFA (FFB) is LOW.
WENA2/LDA WENB2/LDB	Write Enable 2/ Load	1	FIFO A (B) is configured at reset to have either two write enables or programmable flags. If $\overline{LDA}$ ( $\overline{LDB}$ ) is HIGH at reset, this pin operates as a second write enable. If WENA2/ $\overline{LDA}$ (WENB2/ $\overline{LDB}$ ) is LOW at reset this pin operates as a control to load and read the programmable flag offsets for its respective array. If the FIFO is configured to have two write enables, $\overline{WENA1}$ ( $\overline{WENB1}$ ) must be LOW and WENA2 (WENB2) must be HIGH to write data into FIFO A (B). Data will not be written into FIFO A (B) if $\overline{FFA}$ ( $\overline{FFB}$ ) is LOW. If the FIFO is configured to have programmable flags, $\overline{LDA}$ ( $\overline{LDB}$ ) is held LOW to write or read the programmable flag offsets.
QA0-QA8	A Data Outputs	0	9-bit data outputs from RAM array A.
QB0-QB8	B Data Outputs	0	9-bit data outputs from RAM array B.
RCLKA RCLKB	Read Clock	I	Data is read from FIFO A (B) on a LOW-to-HIGH transition of RCLKA (RCLKB) when $\overline{RENA1}$ ( $\overline{RENB1}$ ) and $\overline{RENA2}$ ( $\overline{RENB2}$ ) are asserted.
RENA1 RENB1	Read Enable 1	I	When RENA1 (RENB1) and RENA2 (RENB2) are LOW, data is read from FIFO A (B) on every LOW-to-HIGH transition of RCLKA (RCLKB). Data will not be read from Array A (B) if EFA (EFB) is LOW.
RENA2 RENB2	Read Enable 2	_	When RENA1 (RENB1) and RENA2 (RENB2) are LOW, data is read from the FIFO A (B) on every LOW-to-HIGH transition of RCLKA (RCLKB). Data will not be read from array A (B) if the EFA (EFB) is LOW.
OEA OEB	Output Enable	_	When OEA (OEB) is LOW, outputs DA0-DA8 (DB0-DB8) are active. If OEA (OEB) is HIGH, the outputs DA0-DA8 (DB0-DB8) will be in a high-impedance state.
EFA EFB	Empty Flag	0	When EFA (EFB) is LOW, FIFO A (B) is empty and further data reads from the output are inhibited. When EFA (EFB) is HIGH, FIFO A (B) is not empty. EFA (EFB) is synchronized to RCLKA (RCLKB).
PAEA PAEB	Programmable Almost-Empty Flag	0	When PAEA (PAEB) is LOW, FIFO A (B) is almost-empty based on the offset programmed into the appropriate offset register. The default offset at reset is Empty+7. PAEA (PAEB) is synchronized to RCLKA (RCLKB).
PAFA PAFB	Programmable Almost-Full Flag	0	When $\overline{PAFA}$ ( $\overline{PAFB}$ ) is LOW, FIFO A (B) is almost-full based on the offset programmed into the appropriate offset register. The default offset at reset is Full-7. $\overline{PAFA}$ ( $\overline{PAFB}$ ) is synchronized to WCLKA (WCLKB).
FFA FFB	Full Flag	0	When FFA (FFB) is LOW, FIFO A (B) is full and further data writes into the input are inhibited. When FFA (FFB) is HIGH, FIFO A (B) is not full. FFA (FFB) is synchronized to WCLKA (WCLKB).
VCC	Power		+5V power supply pin.
GND	Ground		0V ground pin.

3034 tbl 01

## **ABSOLUTE MAXIMUM RATINGS**

Symbol	Rating	Com'l & Ind'l	Unit
VTERM	Terminal Voltage with	-0.5 to +7.0	٧
	Respect to GND		
Tstg	StorageTemperature	−55 to +125	°C
lout	DC Output Current	−50 to +50	mA

**NOTE:** 3034 tbl 02

Stresses greater than those listed under ABSOLUTE MAXIMUM RATINGS may cause
permanent damage to the device. This is a stress rating only and functional operation
of the device at these or any other conditions above those indicated in the operational
sections of the specification is not implied. Exposure to absolute maximum rating
conditions for extended periods may affect reliability.

## RECOMMENDED OPERATING CONDITIONS

Symbol	Parameter	Min.	Тур.	Max.	Unit
Voc	Supply Voltage Commercial/Industrial	4.5	5.0	5.5	٧
GND	Supply Voltage	0	0	0	٧
V⊪	Input High Voltage Commercial/Industrial	2.0			٧
V∟	Input Low Voltage Commercial/Industrial	_		0.8	٧
Та	Operating Temperature Commercial	0		70	ç
Та	Operating Temperature Industrial	-40		85	℃

3034 tbl 03

3034 tbl 05

## DC ELECTRICAL CHARACTERISTICS

(Commercial:  $VCC = 5V \pm 10\%$ ,  $TA = 0^{\circ}C$  to  $+70^{\circ}C$ ; Industrial:  $VCC = 5V \pm 10\%$ ,  $TA = -40^{\circ}C$  to  $+85^{\circ}C$ )

			IDT72801 IDT72811 IDT72821 IDT72831 IDT72841 ercial and Indi 10, 12, 15, 25		Comme	IDT72851 ercial and Ind = 15, 20, 25, 3		
Symbol	Parameter	Min.	Тур.	Max.	Min.	Тур.	Max.	Unit
LI <sup>(2)</sup>	Input Leakage Current (Any Input)	<b>-</b> 1	_	1	<b>-</b> 1	_	1	μΑ
ILO <sup>(3)</sup>	Output Leakage Current	-10	_	10	-10	_	10	μΑ
<b>V</b> он	Output Logic "1" Voltage, IOH = -2 mA	2.4	_	_	2.4	_	-	V
<b>V</b> OL	Output Logic "0" Voltage, IOL = 8 mA	_	_	0.4	_	_	0.4	٧
ICC1 <sup>(4,5,6,8)</sup>	Active Power Supply Current (both FIFOs)	_	_	60	_	_	80	mA
ICC2 <sup>(4,7,8)</sup>	Standby Current	_	_	10	_	_	10	mA

#### NOTES:

- 1. Industrial temperature range product for the 25ns speed grade is available as a standard device. All other speed grades are available by special order.
- 2. Measurements with  $0.4 \le V_{IN} \le V_{CC}$ .
- 3.  $\overline{OE} \ge V_{IH}$ ,  $0.4 \le V_{OUT} \le V_{CC}$ .
- 4. Tested with outputs open (IOUT = 0).
- 5. RCLK and WCLK toggle at 20 MHz and data inputs switch at 10 MHz.
- 6. Typical lcc1 =  $2^*[1.7 + 0.7^*fs + 0.02^*CL^*fs]$  (in mA).

These equations are valid under the following conditions:

- Vcc = 5V, TA = 25°C, fs = WCLK frequency = RCLK frequency (in MHz, using TTL levels), data switching at fs/2, CL = capacitive load (in pF).
- 7. All Inputs = Vcc 0.2V or GND + 0.2V, except RCLK and WCLK, which toggle at 20 MHz.
- 8. lcc1 and lcc2 parameters are improved as compared to previous data sheets. To order product for new designs that require the measurements shown in this data sheet, please specify die revision "W" (see Ordering Information).

# **CAPACITANCE** (TA = +25°C, f = 1.0MHz)

Symbol	Parameter	Conditions	Max.	Unit		
CIN <sup>(2)</sup>	Input Capacitance	VIN = 0V	10	pF		
Cour <sup>(1,2)</sup>	Output Capacitance	<b>V</b> OUT = <b>0V</b>	10	pF		

#### NOTE:

- 1. With output deselected ( $\overline{OEA}$ ,  $\overline{OEB} \ge VIH$ ).
- 2. Characterized values, not currently tested.

3034 tbl 04

# **AC ELECTRICAL CHARACTERISTICS**

(Commercial:  $VCC = 5V \pm 10\%$ ,  $TA = 0^{\circ}C$  to  $+70^{\circ}C$ ; Industrial:  $VCC = 5V \pm 10\%$ ,  $TA = -40^{\circ}C$  to  $+85^{\circ}C$ )

					Co		.1				om'l & d'l <sup>(1)</sup>	Come	maraial	
				ı		mmercia I							nercial	ł
			801L10		801L12		801L15				801L25		801L35	
			811L10		811L12		811L15				811L25 821L25		811L35 821L35	
			821L10 831L10		821L12 831L12		821L15 831L15				821L25 831L25		821L35 831L35	
			841L10		841L12		841L15				841L25		841L35	
							851L15	IDT72	851L20		851L25		851L35	
Symbol	Parameter	Min	Max.	Min	Max.	Min	Max.	Min	Max.	Min	Max.	Min	Max.	Unit
fs	Clock Cycle Frequency	_	100	_	83.3	_	66.7	_	50	_	40	_	28.6	MHz
ta	Data Access Time	2	6.5	2	8	2	10	2	12	2	15	2	20	ns
tclk	Clock Cycle Time	10	_	12	_	15	_	20	_	25	_	35	_	ns
tclkh	Clock High Time	4.5	_	5	_	6	_	8	_	10	_	14	_	ns
tclkl	Clock Low Time	4.5	_	5	_	6	_	8	_	10	_	14	_	ns
tos	Data Setup Time	3	_	3	_	4	_	5	_	6	_	7	_	ns
tDН	Data Hold Time	0.5	_	0.5	_	1	_	1	_	1	_	2	_	ns
tens	Enable Setup Time	3	_	3	_	4	_	5	_	6	_	7	_	ns
tenh	Enable Hold Time	0.5	_	0.5	_	1	_	1	_	1	_	2	_	ns
trs	Reset Pulse Width <sup>(2)</sup>	10	_	12	_	15	_	15	_	15	_	35	_	ns
trss	Reset Setup Time	8	_	9	_	10	_	12	_	15	_	20	_	ns
trsr	Reset Recovery Time	8	_	9	_	10	_	12	_	15	_	20	_	ns
trsf	Reset to Flag Time and Output Time	_	10	_	12	_	15	_	20	_	25	_	35	ns
toız	Output Enable to Output in Low-Z(3)	0	_	0	_	0	_	0	_	0	_	0	_	ns
toE	Output Enable to Output Valid	3	6	3	7	3	8	3	10	3	13	3	15	ns
tонz	Output Enable to Output in High-Z <sup>(3)</sup>	3	6	3	7	3	8	3	10	3	13	3	15	ns
twff	Write Clock to Full Flag	_	6.5	_	8	_	10	_	12	_	15	_	20	ns
tref	Read Clock to Empty Flag	_	6.5	_	8	_	10		12	_	15	_	20	ns
tpaf .	Write Clock to Programmable Almost-Full Flag	_	6.5	_	8	_	10	_	12	-	15		20	ns
tpae	Read Clock to Programmable Almost-Empty Flag		6.5	_	8	_	10	_	12	_	15	_	20	ns
tskew1	Skew Time Between Read Clock and Write Clock for Empty Flag and Full Flag	5	_	5	_	6	_	8	_	10	_	12	_	ns
tskew2	Skew Time Between Read Clock and Write Clock for Programmable Almost-Empty Flag and Programmable Almost-Full Flag	14	_	14	_	15	_	16	_	18	_	20	_	ns

#### NOTES:

- 1. Industrial temperature range is available by special order for speed grades faster than 25 ns.
- 2. Pulse widths less than minimum values are not allowed.
- 3. Values guaranteed by design, not currently tested.

# **AC TEST CONDITIONS**

In Pulse Levels	GND to 3.0V
Input Rise/Fall Times	3ns
Input Timing Reference Levels	1.5V
Output Reference Levels	1.5V
Output Load	See Figure 1
	3034 tbl 07

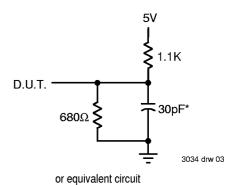


Figure 1. Output Load \*Includes jig and scope capacitances.

## SIGNAL DESCRIPTIONS

FIFO A and FIFOB are identical in every respect. The following description explains the interaction of input and output signals for FIFOA. The corresponding signal names for FIFOB are provided in parentheses.

### **INPUTS:**

**Data In (DA0 – DA8, DB0 – DB8) —** DA0 - DA8 are the nine data inputs for memory array A. DB0 - DB8 are the nine data inputs for memory array B.

# **CONTROLS:**

Reset (RSA, RSB) — Reset of FIFO A (B) is accomplished whenever RSA (RSB) input is taken to a LOW state. During Reset, the internal read and write pointers associated with the FIFO are set to the first location. A Reset is required after power-up before a write operation can take place. The Full Flag FFA (FFB) and Programmable Almost-Full flag PAFA (PAFB) will be reset to HIGH after tRSF. The Empty Flag EFA (EFB) and Programmable Almost-Empty flag PAEA (PAEB) will be reset to LOW after tRSF. During Reset, the output register is initialized to all zeros and the offset registers are initialized to their default values.

Write Clock (WCLKA, WCLKB) — A write cycle to Array A (B) is initiated on the LOW-to-HIGH transition of WCLKA (WCLKB). Data setup and hold times must be met with respect to the LOW-to-HIGH transition of WCLKA (WCLKB). The Full Flag FFA (FFB) and Programmable Almost-Full flag PAFA (PAFB) are synchronized with respect to the LOW-to-HIGH transition of the Write Clock WCLKA (WCLKB).

The Write and Read Clocks can be asynchronous or coincident.

Write Enable 1 (WENA1, WENB1) — If FIFO A (B) is configured for programmable flags, WENA1 (WENB1) is the only enable control pin. In this configuration, when WENA1 (WENB1) is LOW, data can be loaded into the input register of RAM Array A (B) on the LOW-to-HIGH transition of every Write Clock WCLKA (WCLKB). Data is stored in Array A (B) sequentially and independently of any ongoing read operation.

In this configuration, when  $\overline{WENA1}$  ( $\overline{WENB1}$ ) is HIGH, the input register holds the previous data and no new data is allowed to be loaded into the register.

If the FIFO is configured to have two write enables, which allows for depth expansion. See Write Enable 2 paragraph below for operation in this configuration.

To prevent data overflow,  $\overline{FFA}$  ( $\overline{FFB}$ ) will go LOW, inhibiting further write operations. Upon the completion of a valid read cycle, the  $\overline{FFA}$  ( $\overline{FFB}$ ) will go HIGH after twff, allowing a valid write to begin.  $\overline{WENA1}$  ( $\overline{WENB1}$ ) is ignored when FIFO A (B) is full.

Read Clock (RCLKA, RCLKB) — Data can be read from Array A (B) on the LOW-to-HIGH transition of RCLKA (RCLKB). The Empty Flag EFA (EFB) and Programmable Almost-Empty Flag PAEA (PAEB) are synchronized with respect to the LOW-to-HIGH transition of RCLKA (RCLKB). The Write and Read Clocks can be asynchronous or coincident.

Read Enables (RENA1, RENA2, RENB1, RENB2) — When both Read Enables RENA1, RENA2 (RENB1, RENB2) are LOW, data is read from Array A(B) to the output register on the LOW-to-HIGH transition of the Read Clock RCLKA (RCLKB).

When either of the two Read Enable RENA1, RENA2 (RENB1, RENB2) associated with FIFO A (B) is HIGH, the output register holds the previous data and no new data is allowed to be loaded into the register.

When all the data has been read from FIFO A (B), the Empty Flag EFA (EFB) will go LOW, inhibiting further read operations. Once a valid write operation has been accomplished, EFA (EFB) will go HIGH after tREF and a valid read can begin. The Read Enables RENA1, RENA2 (RENB1, RENB2) are ignored when FIFO A (B) is empty.

Output Enable  $(\overline{OEA}, \overline{OEB})$  — When Output Enable  $\overline{OEA}$   $(\overline{OEB})$  is enabled (LOW), the parallel output buffers of FIFOA (B) receive data from their respective output register. When Output Enable  $\overline{OEA}$   $(\overline{OEB})$  is disabled (HIGH), the QA (QB) output data bus is in a high-impedance state.

Write Enable 2/Load (WENA2/LDA, WENB2/LDB) — This is a dual-purpose pin. FIFO A (B) is configured at Reset to have programmable flags or to have two write enables, which allows depth expansion. If WENA2/LDA (WENB2/LDB) is set HIGH at Reset RSA = LOW (RSB = LOW), this pin operates as a second write enable pin.

If FIFO A (B) is configured to have two write enables, when Write Enable 1  $\overline{\text{WENA1}}$  (WENB1) is LOW and WENA2/ $\overline{\text{LDA}}$  (WENB2/ $\overline{\text{LDB}}$ ) is HIGH, data can be loaded into the input register and RAM array on the LOW-to-HIGH transition of every Write Clock WCLKA (WCLKB). Data is stored in the array sequentially and independently of any ongoing read operation.

In this configuration, when WENA1 (WENB1) is HIGH and/or WENA2/LDA (WENB2/LDB) is LOW, the input register of Array A holds the previous data and no new data is allowed to be loaded into the register.

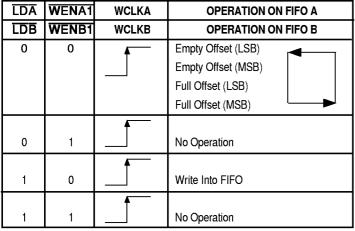
To prevent data overflow, the Full Flag FFA (FFB) will go LOW, inhibiting further write operations. Upon the completion of a valid read cycle, FFA (FFB) will go HIGH after tWFF, allowing a valid write to begin. WENA1, (WENB1) and WENA2/LDA (WENB2/LDB) are ignored when the FIFO is full.

FIFO A (B) is configured to have programmable flags when the WENA2/ $\overline{\text{LDA}}$  (WENB2/ $\overline{\text{LDB}}$ ) is set LOW at Reset  $\overline{\text{RSA}}$  = LOW ( $\overline{\text{RSB}}$  = LOW). Each FIFO contains four 8-bit offset registers which can be loaded with data on the inputs, or read on the outputs. See Figure 3 for details of the size of the registers and the default values.

If FIFO A (B) is configured to have programmable flags, when the  $\overline{\text{WENA1}}$  (WENB1) and WENA2/ $\overline{\text{LDA}}$  (WENB2/ $\overline{\text{LDB}}$ ) are set LOW, data on the DA (DB) inputs are written into the Empty (Least Significant Bit) Offset register on the first LOW-to-HIGH transition of the WCLKA (WCLKB). Data are written into the Empty (Most Significant Bit) Offset register on the second LOW-to-HIGH transition of WCLKA (WCLKB), into the Full (Least Significant Bit) Offset register on the third transition, and into the Full (Most Significant Bit) Offset register on the fourth transition. The fifth transition of WCLKA (WCLKB) again writes to the Empty (Least Significant Bit) Offset register.

However, writing all offset registers does not have to occur at one time. One or two offset registers can be written and then by bringing  $\overline{\text{LDA}}$  ( $\overline{\text{LDB}}$ ) HIGH, FIFO A (B) is returned to normal read/write operation. When  $\overline{\text{LDA}}$  ( $\overline{\text{LDB}}$ ) is set LOW, and  $\overline{\text{WENA1}}$  ( $\overline{\text{WENB1}}$ ) is LOW, the next offset register in sequence is written.

The contents of the offset registers can be read on the QA (QB) outputs when WENA2/ $\overline{\text{LDA}}$  (WENB2/ $\overline{\text{LDB}}$ ) is set LOW and both Read Enables RENA1, RENA2 (RENB1, RENB2) are set LOW. Data can be read on the LOW-to-HIGH transition of the Read Clock RCLKA (RCLKB).



NOTE:

3034 tbl 08

- 1. For the purposes of this table,  $\overline{WENA1}$  and  $\overline{WENB1}$  = VIH.
- The same selection sequence applies to reading from the registers. RENA1 and RENA2 (RENB1 and RENB2) are enabled and read is performed on the LOW-to-HIGH transition of RCLKA (RCLKB).

Figure 2. Writing to Offset Registers for FIFOs A and B

A read and write should not be performed simultaneously to the offset registers.

### **OUTPUTS:**

Full Flag (FFA, FFB) — FFA (FFB) will go LOW, inhibiting further write operations, when Array A (B) is full. If no reads are performed after reset, FFA (FFB) will go LOW after 256 writes to the IDT72801's FIFO A (B);512 writes to the IDT72811's FIFO A (B); 1,024 writes to the IDT72821's FIFO A (B); 2,048 writes to the IDT72831's FIFO A (B); 4,096 writes to the IDT72841's FIFO A (B); or 8,192 writes to the IDT72851's FIFO A (B).

FFA (FFB) is synchronized with respect to the LOW-to-HIGH transition of the Write Clock WCLKA (WCLKB).

**Empty Flag (EFA, EFB)** — EFA (EFB) will go LOW, inhibiting further read operations, when the read pointer is equal to the write pointer, indicating that Array A (B) is empty.

EFA (EFB) is synchronized with respect to the LOW-to-HIGH transition of the Read Clock RCLKA (RCLKB).

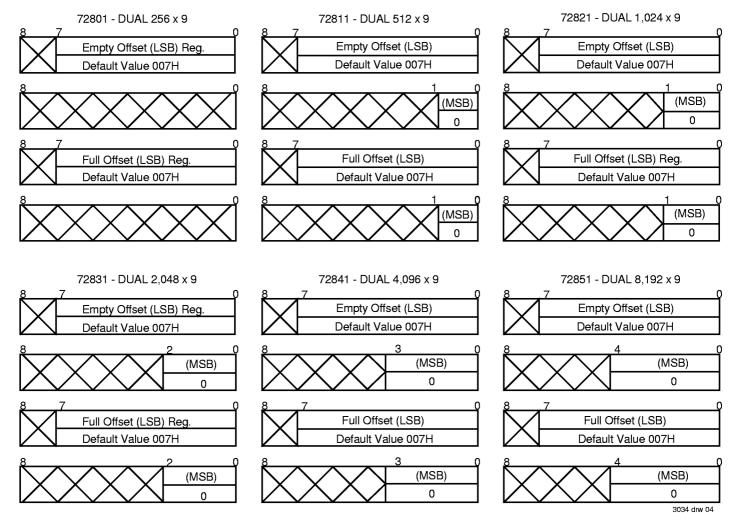


Figure 3. Offset Register Formats and Default Values for the A and B FIFOs

Programmable Almost–Full Flag (PAFA, PAFB) — PAFA (PAFB) will go LOW when the amount of data in Array A (B) reaches the almost-full condition. If no reads are performed after Reset, PAFA (PAFB) will go LOW after (256-m) writes to the IDT72801's FIFO A (B); (512-m) writes to the IDT72811's FIFO A (B); (1,024-m) writes to the IDT72821's FIFO A (B); (2,048-m) writes to the IDT72831's FIFO A (B); or (8,192-m) writes to the IDT72851's FIFO A (B).

FFA (FFB) is synchronized with respect to the LOW-to-HIGH transition of the Write Clock WCLKA (WCLKB). The offset "m" is defined in the Full Offset registers.

If there is no Full offset specified,  $\overline{\text{PAFA}}$  ( $\overline{\text{PAFB}}$ ) will go LOW at Full-7 words.

PAFA (PAFB) is synchronized with respect to the LOW-to-HIGH transition of WCLKA (WCLKB).

Programmable Almost–Empty Flag (PAEA, PAEB) — PAEA (PAEB) will go LOW when the read pointer is "n+1" locations less than the write pointer. The offset "n" is defined in the Empty Offset registers. If no reads are performed after Reset, PAEA (PAEB) will go HIGH after "n+1" writes to FIFO A (B).

If there is no Empty offset specified,  $\overline{PAEA}$  ( $\overline{PAEB}$ ) will go LOW at Empty+7 words.

PAEA (PAEB) is synchronized with respect to the LOW-to-HIGH transition of the Read Clock RCLKA (RCLKB).

**Data Outputs (QAo – QAs, QBo – QBs)** — QAo - QAs are the nine data outputs for memory array A, QBo - QBs are the nine data outputs for memory array B.

TABLE 1: STATUS FLAGS FOR A AND B FIFOS

NU	JMBER OF WORDS IN ARRAY	/ A	FFA	PAFA	PAEA	EFA
NU	JMBER OF WORDS IN ARRAY	/ B	FFB	PAFB	PAEB	EFB
72801	72811	72821				
0	0	0	Н	Н	L	L
1 to n <sup>(1)</sup>	1 to n <sup>(1)</sup>	1 to n <sup>(1)</sup>	Н	Н	L	Н
(n+1) to (256-(m+1))	(n+1) to (512-(m+1))	(n+1) to (1,024-(m+1))	Н	Н	Н	Н
(256-m) <sup>(2)</sup> to 255	(512-m) <sup>(2)</sup> to 511	(1,024-m) <sup>(2)</sup> to 1,023	Н	L	Н	Н
256	512	1,024	L	L	Н	Н

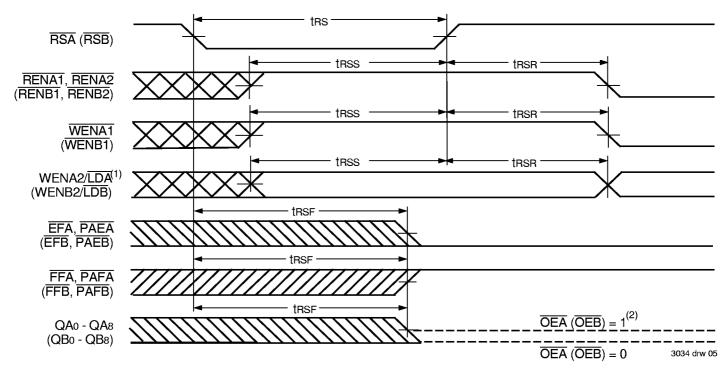
NU	MBER OF WORDS IN ARRAY	Y A	FFA	PAFA	PAEA	EFA
NU	MBER OF WORDS IN ARRAY	Y B	FFB	PAFB	PAEB	EFB
72831	72841	72851				
0	0	0	Н	Н	L	L
1 to n <sup>(1)</sup>	1 to n <sup>(1)</sup>	1 to n <sup>(1)</sup>	Н	Н	L	Н
(n+1) to (2,048-(m+1))	(n+1) to (4,096-(m+1))	(n+1) to (8,192-(m+1))	Н	Н	Н	Н
(2,048-m) <sup>(2)</sup> to 2,047	(4,096-m) <sup>(2)</sup> to 4,095	(8,192-m) <sup>(2)</sup> to 8,191	Н	L	Н	Н
2,048	4,096	8,192	L	L	Н	Н

NOTES:

3034 tbl 09

1. n = Empty Offset (n = 7 default value)

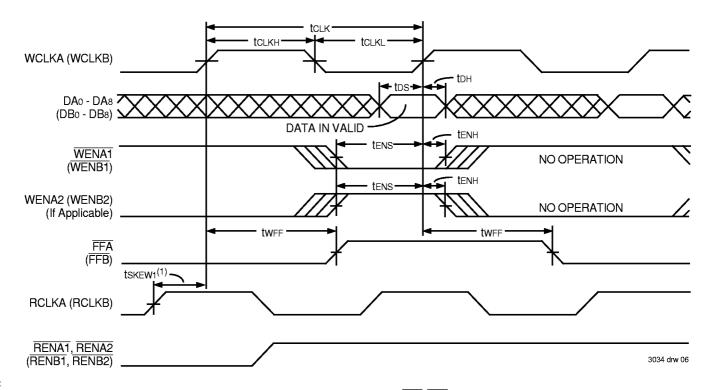
2. m = Full Offset (m = 7 default value)



#### NOTES:

- 1. Holding WENA2/LDA (WENB2/LDB) HIGH during reset will make the pin act as a second write enable pin. Holding WENA2/LDA (WENB2/LDB) LOW during reset will make the pin act as a load enable for the programmable flag offset registers.
- 2. After reset, QA0 QA8 (QB0 QB8) will be LOW if OEA (OEB) = 0 and tri-state if OEA (OEB) = 1.
- 3. The clocks RCLKA, WCLKA (RCLKB, WCLKB) can be free-running during reset.

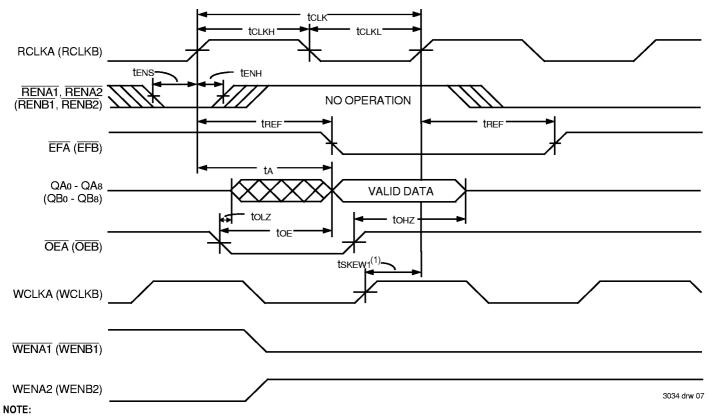
Figure 4. Reset Timing



#### NOTE:

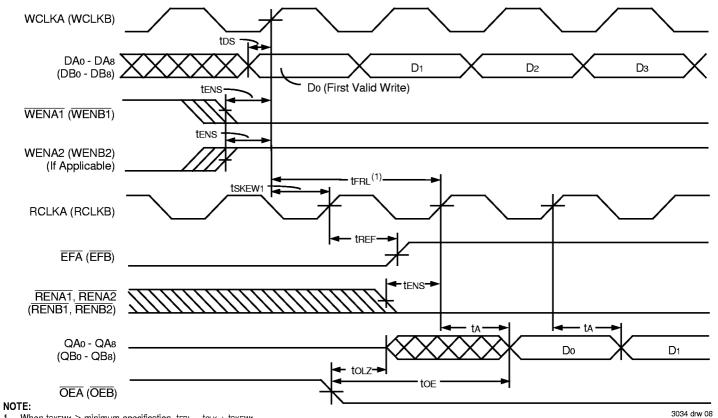
1. tskewt is the minimum time between a rising RCLKA (RCLKB) edge and a rising WCLKA (WCLKB) edge for FFA (FFB) to change during the current clock cycle. If the time between the rising edge of RCLKA (RCLKB) and the rising edge of WCLKA (WCLKB) is less than tskewt, then FFA (FFB) may not change state until the next WCLKA (WCLKB) edge.

Figure 5. Write Cycle Timing



1. tskewi is the minimum time between a rising WCLKA (WCLKB) edge and a rising RCLKA (RCLKB) edge for EFA (EFB) to change during the current clock cycle. If the time between the rising edge of RCLKA (RCLKB) and the rising edge of WCLKA (WCLKB) is less than tskewi, then EFA (EFB) may not change state until the next RCLKA (RCLKB)

Figure 6. Read Cycle Timing

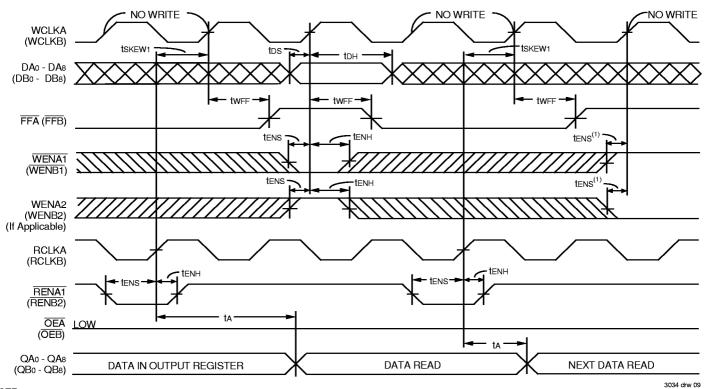


1. When tskew1 ≥ minimum specification, tFRL = tclk + tskew1

tskew1 < minimum specification, tfrL = 2tclk + tskew1v or tclk + tskew1

The Latency Timings apply only at the Empty Boundary (EFA, EFB = LOW).

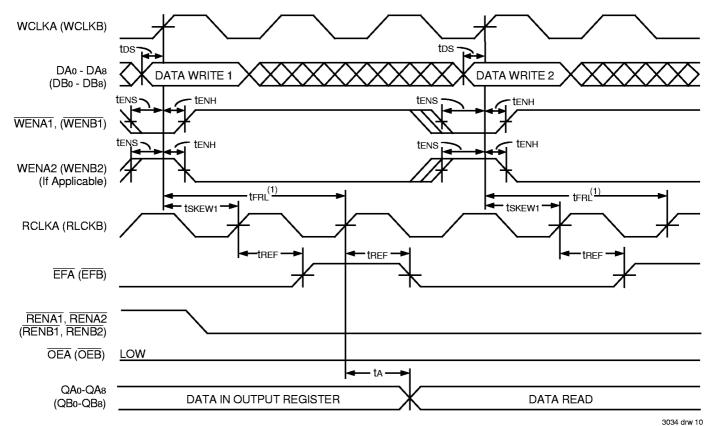
Figure 7. First Data Word Latency Timing



NOTE:

1. Only one of the two write enable inputs, WEN1 or WEN2, needs to go inactive to inhibit writes to the FIFO.

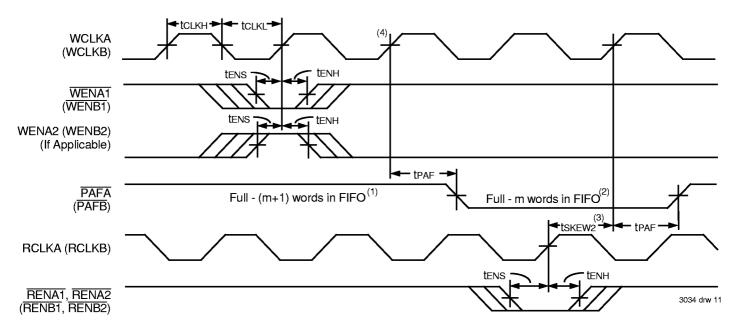
Figure 8. Full Flag Timing



NOTE:

When tskewi ≥ minimum specification, tfrl maximum = tclk + tskewi tskewi < minimum specification, tfrl maximum = 2tclk + tskewi or tclk + tskewi.</li>
 The Latency Timings apply only at the Empty Boundary (EFA, EFB = LOW).

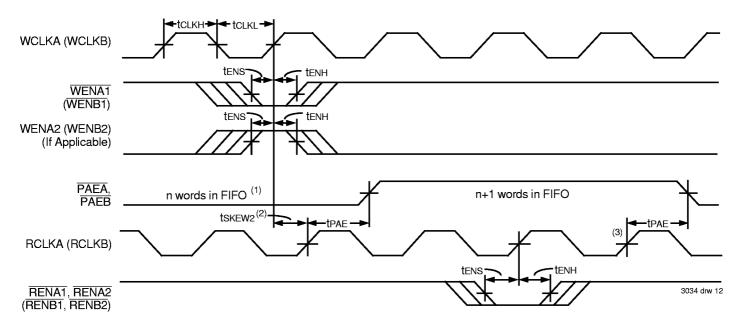
Figure 9. Empty Flag Timing



#### NOTES:

- 1.  $m = \overline{PAF}$  offset.
- 2. (256-m) words for the IDT72801; (512-m) words the IDT72811; (1,024-m) words for the IDT72821; (2,048-m) words for the IDT72831; (4,096-m) words for the IDT72841; or (8,192-m) words for the IDT72851.
- 3. tskewz is the minimum time between a rising RCLKA (RCLKB) edge and a rising WCLKA (WCLKB) edge for PAFA (PAFB) to change during that clock cycle. If the time between the rising edge of RCLKA (RCLKB) and the rising edge of WCLKA (WCLKB) is less than tskewz, then PAFA (PAFB) may not change state until the next WCLKA (WCLKB) rising edge.
- 4. If a write is performed on this rising edge of the write clock, there will be Full (m-1) words in FIFO A (B) when PAFA (PAFB) goes LOW.

Figure 10. Programmable Full Flag Timing



## NOTES:

- 1. n = PAE offset.
- 2. tskewz is the minimum time between a rising WCLKA (WCLKB) edge and a rising RCLKA (RCLKB) edge for PAEA (PAEB) to change during that clock cycle. If the time between the rising edge of WCLKA (WCLKB) and the rising edge of RCLKA (RCLKB) is less than tskewz, then PAEA (PAEB) may not change state until the next RCLKA (RCLKB) rising edge.
- 3. If a read is performed on this rising edge of the read clock, there will be Empty + (n-1) words in FIFO A (B) when PAEA (PAEB) goes LOW.

Figure 11. Programmable Empty Flag Timing

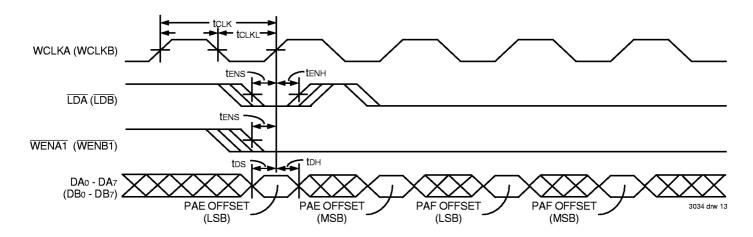


Figure 12. Write Offset Register Timing

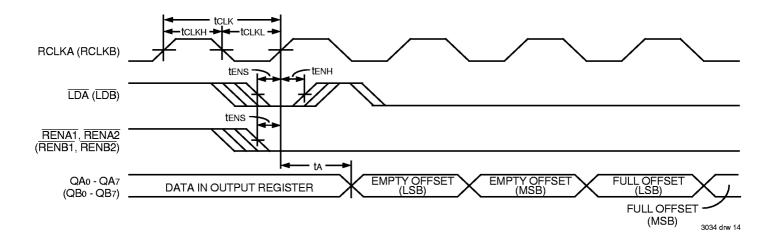


Figure 13. Read Offset Register Timing

## **OPERATING CONFIGURATIONS**

SINGLE DEVICE CONFIGURATION — When FIFO A (B) is in a Single Device Configuration, the Read Enable 2 RENA2 (RENB2) control input

can be grounded (see Figure 14). In this configuration, the Write Enable 2/Load WENA2/LDA (WENB2/LDB) pin is set LOW at Reset so that the pin operates as a control to load and read the programmable flag offsets.

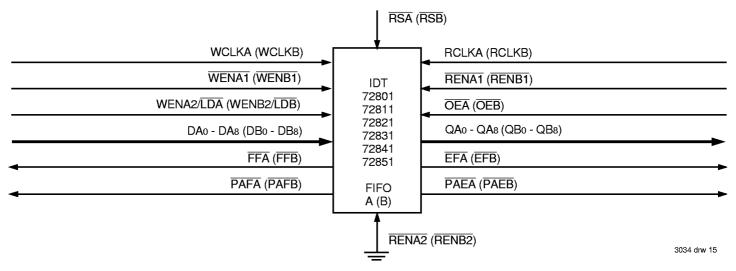


Figure 14. Block Diagram of One of the IDT72801/72811/72821/72831/72841/72851's two FIFOs configured as a single device

WIDTH EXPANSION CONFIGURATION — Word width may be increased simply by connecting the corresponding input control signals of FIFOs A and B. A composite flag should be created for each of the endpoint status flags  $\overline{EFA}$  and  $\overline{EFB}$ , also  $\overline{FFA}$  and  $\overline{FFB}$ ). The partial status flags  $\overline{PAEA}$ ,  $\overline{PAEA}$  and  $\overline{PAFB}$  can be detected from any one device. Figure 15 demonstrates an 18-bit word width using the two FIFOs contained in one IDT72801/72811/72821/72831/72841/72851. Any word width can

be attained by adding additional IDT72801/72811/72821/72831/72841/72851s

When these devices are in a Width Expansion Configuration, the Read Enable 2 (RENA2 and RENB2) control inputs can be grounded (see Figure 15). In this configuration, the Write Enable 2/Load (WENA2/LDA, WENB2/LDB) pins are set LOW at Reset so that the pin operates as a control to load and read the programmable flag offsets.

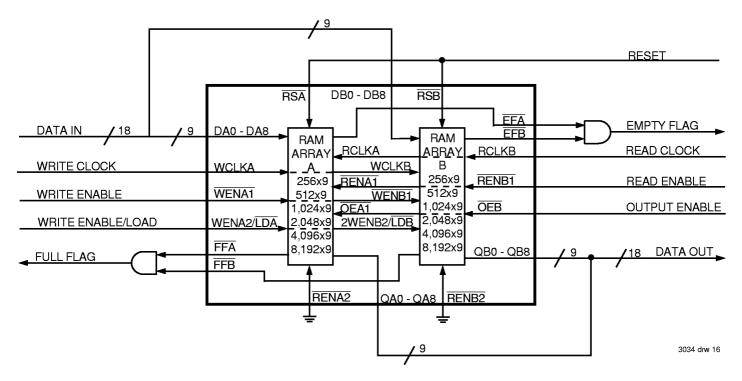


Figure 15. Block diagram of the two FIFOs contained in one IDT72801/72811/72821/72831/72841/72851 configured for an 18-bit width-expansion

# TWO PRIORITY DATA BUFFER CONFIGURATION

The two FIFOs contained in the IDT72801/72811/72821/72831/72841/72851 can be used to prioritize two different types of data shared on a system bus. When writing from the bus to the FIFO, control logic sorts the intermixed

data according to type, sending one kind to FIFO A and the other kind to FIFO B. Then, at the outputs, each data type is transferred to its appropriate destination. Additional IDT72801/72811/72821/72831/72841/72851s permit more than two priority levels. Priority buffering is particularly useful in network applications.

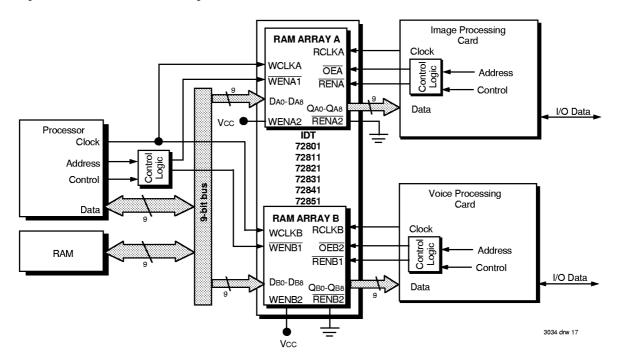


Figure 16. Block Diagram of Two Priority Configuration

### **BIDIRECTIONAL CONFIGURATION**

The two FIFOs of the IDT72801/72811/72821/72831/72841/72851 can be used to buffer data flow in two directions. In the example that follows, a

processor can write data to a peripheral controller via FIFO A, and, in turn, the peripheral controller can write the processor via FIFO B.

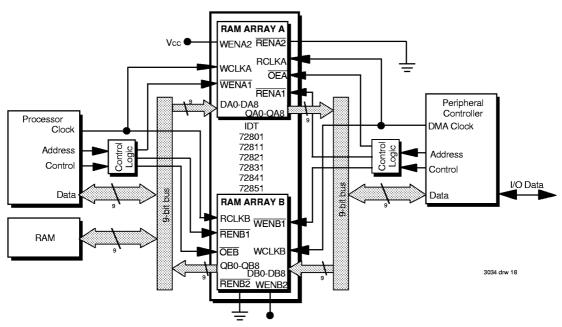


Figure 17. Block Diagram of Bidirectional Configuration

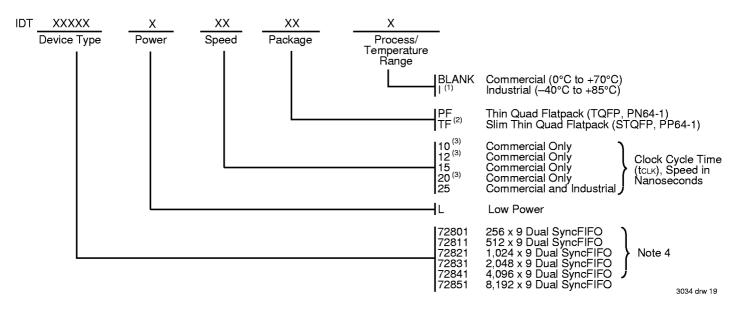
**DEPTH EXPANSION**— IDT72801/72811/72821/72831/72841/72851 can be adapted to applications that require greater than 256/512/1,024/2,048/4,096/8,192 words. The existence of double enable pins on the read and write ports allow depth expansion. The Write Enable 2/Load (WENA2, WENB2) pins are used as a second write enables in a depth expansion configuration, thus the Programmable flags are set to the default values. Depth expansion is possible by using one enable input for system control while the other enable input is controlled by expansion logic to direct the flow of data. A typical application would have the expansion logic alternate data

access from one device to the next in a sequential manner. These FIFOs operate in the Depth Expansion configuration when the following conditions are met:

- 1. WENA2/LDA and WENB2/LDB pins are held HIGH during Reset so that these pins operate as second Write Enables.
- 2. External logic is used to control the flow of data.

Please see the Application Note" DEPTH EXPANSION OF IDT'S SYN-CHRONOUS FIFOS USING THE RING COUNTER APPROACH" for details of this configuration.

## **ORDERING INFORMATION**



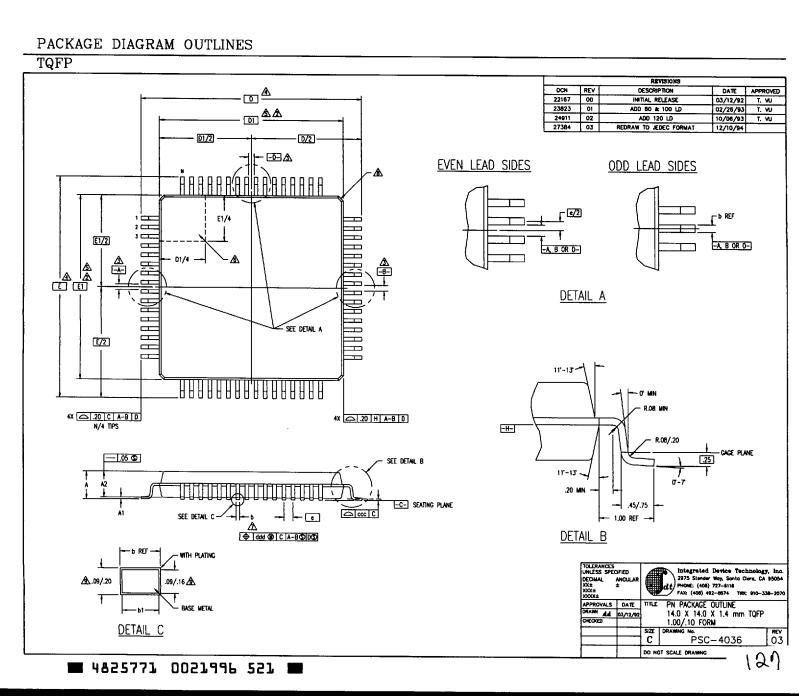
#### NOTES:

- 1. Industrial temperature range is available by special order for speed grades faster than 25ns.
- 2. The STQFP package is not available for the IDT72851.
- 3. The 20ns speed grade is only available for the IDT72851; however, this device is not available in the 10ns or 12ns speed grade.
- 4. To order die revision "W" (improved ICC specs), please specify SCDS-W after the part number.



2975 Stender Way Santa Clara, CA 95054 800-345-7015 fax: 408-492-8674 www.idt.com

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# PACKAGE DIAGRAM OUTLINES

# TQFP (Continued)

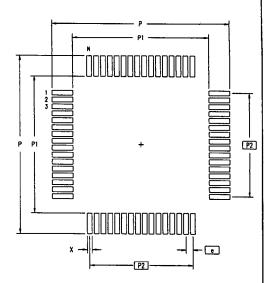
	DWG #		PN64-	1	DWC	G #	PN80	-1	DW	G /	PN10	0-1	DW	3 <b>#</b>	PN12	0-1												
Ş	JEDE	C VARIAT	ION	Z	JEDE	C VARIAT	ION	N	JEDE	C VARIAT	ION	N	JEDE	C VARIAT	ION													
B		BP		P		BQ		] P		BR		1 9 1		BS		P												
,	MIN	NOM	MAX	E	MIN	NOM	MAX	É	MIN	NOM	MAX	] É	MIN	NOM	MAX	Ė												
A	-		1.60		_	-	1.60		-	- <sup>-</sup>	1.60			-	1.60													
A1	.05	.10	.15		.05	.10	.15		.05	.10	.15	П	.05	.10	.15													
A2	1.35	1.40	1.45		1.35	1.40	1.45		1.35	1.40	1.45		1.35	1.40	1.45													
٥		6.00 BS	C	4	16.00 BSC		4	16.00 BSC		4		6.00 85	c	4														
01	1	14.00 BS	С	5,2	1	14.00 BSC		5,2	14.00 BSC		5,2	14.00 BSC		C	5,2													
E	1	16.00 BS	C	4	1	6.00 85	С	4	16.00 BSC		4	16.00 BSC		C	4													
E١	.1	4.00 BS	С	5,2	1	4.00 BS	С	5,2		14.00 BSC				14.00 BS	iC .	5.2												
N		64			80		80		80		80		80		80		80		80			100		П		120		
e		.80 BSC			.65 BSC				.50 BSC			.40 BSC																
Ь	.30	.37	.45	7	.22 .32 .38		7	.17	.22	.27	7	.13	.18	.23	7													
ы	.30	.35	.40		.22	.30	.33		.17	.20	.23		.13	.16	.19	1												
ccc	-	-	.10		-	_	.10	1	-	i -	.08	$\Box$	_	<del>  -</del>	.08													
ppp	-	_	.20		-	-	.13		-	<b> </b>	.08		-	-	.07	1-												

## NOTES:

- 1 ALL DIMENSIONING AND TOLERANCING CONFORM TO ANSI Y14.5M-1982
- TOP PACKAGE MAY BE SMALLER THAN BOTTOM PACKAGE BY .15 mm
- ⚠ DATUMS A-B AND -D- TO BE DETERMINED AT DATUM PLANE -H-
- Δ DIMENSIONS D AND ε ARE TO BE DETERMINED AT SEATING PLANE -C-
- DIMENSIONS D1 AND E1 DO NOT INCLUDE MOLD PROTRUSION. ALLOWABLE MOLD PROTRUSION IS .25 mm PER SIDE. D1 AND E1 ARE MAXIMUM BODY SIZE DIMENSIONS INCLUDING MOLD MISMATCH
- DETAILS OF PIN 1 IDENTIFIER IS OPTIONAL BUT MUST BE LOCATED WITHIN THE ZONE INDICATED
- DIMENSION 6 DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION IS .08 mm in excess of the 6 dimension at maximum material condition. Dambar cannot be located on the lower radius or the foot.
- A EXACT SHAPE OF EACH CORNER IS OPTIONAL
- THESE DIMENSIONS APPLY TO THE FLAT SECTION OF THE LEAD BETWEEN .10 AND .25 mm FROM THE LEAD TIP
- 10 ALL DIMENSIONS ARE IN MILLIMETERS
- 11 This outline conforms to jedec publication 95 registration MO-136, variation 8P, 8Q, 8R & 8S

	REVISIONS										
DCN	REV	DESCRIPTION	DATE	APPROVED							
22167	00	INITIAL RELEASE	03/12/92	T. VU							
23823	01	ADD 80 & 100 LD	02/26/93	T. VU							
24911	02	ADD 120 LD	10/06/93	T. VU							
27384	03	REDRAW TO JEDEC FORMAT	11/18/94								

# LAND PATTERN DIMENSIONS

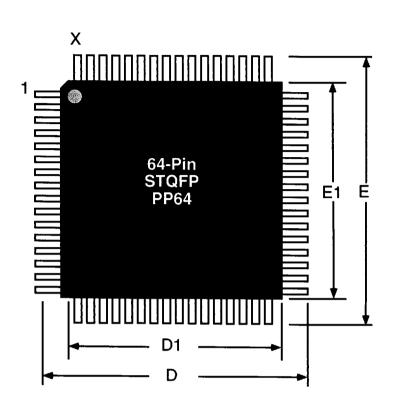


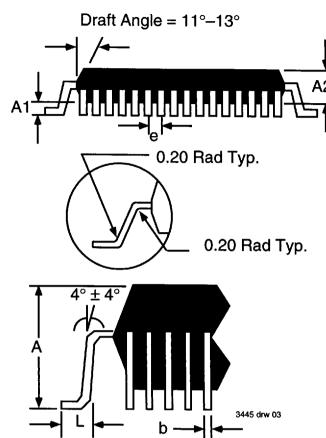
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ď	16.80	17.00	16.80	17.00	16.80	17.00	16.80	17.00	
P1	13.80	14.00	13.80	14.00	13.80	14.00	13.80	14.00	
P2	12.00	BSC	12.35 BSC		12.00	BSC	11.60 BSC		
Χ	.40	.60	.30	.50	.30	40	.20	.30	
e	.80 (	SC	.65 BSC		.50 (	3SC	.40 BSC		
N	6	4	80		100		120		

TOLERANCES UNLESS SPE DECIMAL XX± XXX± XXXX±	CIRED ANGULAR ±		Integrated Device Technology 2975 Stender Way, Santa Clore, CA 4 PHONE: (408) 727-5116 FAM: (408) 492-8874 TWM: 910-33	95054
APPROVALS	DATE	TITLE	PN PACKAGE OUTLINE	
DRAWN ALA	03/12/92		14.0 X 14.0 X 1.4 mm TQFP	
CHECKED	· · · ·		1.00/.10 FORM	
		SIZE	DRAWING No.	REV
		С	PSC-4036	03
		DO NO	OT SCALE DRAWING	CX_
			la	K

**■** 4825771 0021997 468 **■** 

# **PACKAGE DIMENSIONS**





# **DIMENSIONS**

**64-PIN STQFP WITH 10MM BODY** 

Discouries T. J. St				
DImension	Tolerance	Dimension		
Letter	(mm)	(mm)		
A	Max.	1.60		
A1	<u>+</u> .05	0.10		
A2	<u>+</u> .05	1.45		
D	<u>+</u> .10	12.00		
D1	<u>+</u> .10	10.00		
E	<u>+</u> .10	12.00		
E1	<u>+</u> .10	10.00		
L	<u>+</u> 15	0.60		
е	Basic	0.50		
b	.05	0.22		